FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16822

Generic Copy

Issue Date: 29-Feb-2012

TITLE: Qualification of ISMF Fab in Seremban (Malaysia) for backgrind and TiNiAuSn backmetal process for CREE wafer sales devices.

PROPOSED FIRST SHIP DATE: 29-May-2012 or earlier with customer approval

AFFECTED CHANGE CATEGORY(S): Fab for Backgrind & TiNiAuSn Backmetal process

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or Suei Huey Wong<SueiHuey.Wong@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office or Suei Huey Wong<SueiHuey.Wong@onsemi.com>

ADDITIONAL RELIABILITY DATA: Available
Contact your local ON Semiconductor Sales Office or <francis.lualhati@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to the implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

ON Semiconductor is pleased to announce that all CREE wafer sales devices are now qualified for backgrind and TiNiAuSn backmetal process in ISMF Fab in Seremban, Malaysia.

Upon expiration or approval of the Final PCN, devices may be supplied from ISMF.

ISMF is compliant to TS16949, ISO-9001 and ISO-14000. The devices have previously been manufactured at Chipbond. Devices are now qualified to run at ISMF for backgrind & TiNiAuSn backmetal process.

Qualification tests are designed to show that the reliability of transferred devices will continue to meet or exceed ON Semiconductor standards.

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RELIABILITY DATA SUMMARY:

Test:	Conditions:	Interval:	Results
TC+PC	Ta= -40 C to 125 C	1000 cyc	0/480
TC+PC	Ta= -65 C to 150 C	1000 cyc	0/480

ELECTRICAL CHARACTERISTIC SUMMARY:

Available upon request

CHANGED PART IDENTIFICATION:

Products listed in this PCN with Finished Good date codes representing WW21, 2012 or later will be processed in ISMF, unless earlier customer approval is obtained. If early customer approval is obtained, devices with date codes of WW09, 2011 or later will be processed in ISMF.

List of affected Generic Parts:

HBL21000RP
HBL21000WP

List of affected Customer Specific Parts:

FCDN608-TKY
FCDN605-TKY
FCDN614-UBM